

IN THE CLAIMS:

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~striketrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

**Please cancel claims 1-24 and add new claims 25-48 in accordance with the following:**

1-24 cancelled

25. (New) A method for disposing a conductor structure on a substrate, comprising:  
establishing a separable connection between a transfer support and the conductor structure;

joining together the transfer support and the conductor structure to the substrate, to form a connection between the conductor structure and the substrate which connection is stronger than the separable connection between the transfer support and the conductor structure; and  
separating the separable connection between the transfer support and the conductor structure, with the connection being left between the conductor structure and the substrate.

26. (New) The method in accordance with claim 25, wherein the conductor structure has nanotubes.

27. (New) The method in accordance with claim 26, wherein the nanotubes are aligned in at least one section of the conductor structure.

28. (New) The method in accordance with claim 26, wherein the nanotubes are formed of a material selected from the group consisting of aluminum nitride, boron nitride and carbon.

29. (New) The method in accordance with claim 26, wherein the nanotubes are substantially identical.

30. (New) The method in accordance with claim 26, wherein each of the nanotubes has at least one functionalized point.

31. (New) The method in accordance with claim 25, wherein transfer support has at least one transfer support substance that supports the conductor structure for establishing the separable connection between the transfer support and the conductor structure.

32. (New) The method in accordance with claim 31, wherein the transfer support substance is functionalized for creating a transfer support contact point on the transfer support substance.

33. (New)] The method in accordance with claim 32, wherein the transfer support substance is functionalized with at least one sulfur atom.

34. (New) The method in accordance with 31, wherein a macro molecule is used as the transfer support substance.

35. (New) The method in accordance with claim 34, wherein the macro molecule is selected from the group consisting of deoxyribonucleic acid and a protein.

36. (New) The method in accordance with claim 34, wherein the macro molecule is stretched lengthwise.

37. (New) The method in accordance with claim 34, wherein a folded macro molecule is used which is stretched before the transfer support is joined together with the conductor structure.

38. (New) The method in accordance with claim 37, wherein the folded macro molecule is stretched with the aid of a flowing fluid.

39. (New) The method in accordance with claim 25, wherein the substrate has an electrical contact surface between the conductor structure and the substrate.

40. (New) The method in accordance with claim 25 wherein before the transfer support and conductor structure are joined to the substrate, the substrate is functionalized to form a substrate contact surface.

41. (New) The method in accordance with claim 40, wherein gold is applied to the substrate to form the substrate contact surface.

42. (New) The method in accordance with claim 25, with an adhesive layer is used to between the transfer support and the conductor structure and/or between the conductor structure and the substrate.

43. (New) The method in accordance with claim 25, wherein the substrate is selected from the group consisting of a semiconductor substrate and a plastic substrate.

44. (New) An electrical device comprising:  
a substrate having at least first and second contact surfaces; and  
a conductor structure connected to the first and second contact surfaces of the substrate, the conductor structure having nanotubes which are aligned to extend from the first contact surface to the second contact surface.

45. (New) The electrical device in accordance with claim 44, wherein the conductor structure is an electrical conductor structure.

46. (New) The electrical device in accordance with claim 44, wherein the nanotubes are formed of a material selected from the group consisting of aluminum nitride, boron nitride and carbon.

47. (New) The electrical device in accordance with claim 44, wherein all of the nanotubes are substantially identical.

48. (New) The electrical device in accordance with claim 44, with the substrate is formed of a material selected from the group consisting of a semiconductor material and a plastic material.